

Nomenclature for DRAM Component

Ver.4.7

1		2		3		4		5		6		7		8		9		10		11		12		13		14		15		16		17		18													
SC		B		15		H		1G		80		0		A		F		-		25		D		I																							
Identifier SC = UniIC Identifier																								Operating Temperature I = Industrial Temperature chip (DDR2, DDR3,LP DDR4/X: -40°C ~ +95°C; SDR, DDR, LP DDR2,LP DDR3: -40°C ~ +85°C) Blank = Commercial Temperature chip (DDR2, DDR3, DDR4: 0°C ~ +95°C; LP DDR2/LP DDR3: 0°C ~ +85°C; LP DDR4/X: -25-85°C; SDR, DDR: 0°C ~ +70°C) A3 = Automotive grade 3(-40°C ~ +95°C); LPDDR4(-40°C ~ +85°C) A2 = Automotive grade 2(-40°C ~ +105°C) A25 = Automotive grade 2(-40°C ~ +115°C) A1 = Automotive grade 1(-40°C ~ +125°C) X = High-Rel grade (-55°C ~ +125°C)																							
Product Group B = Commodity chip E = ECC chip X = Extra Robustness ECC chip N = Consumer chip																								Latencies A = 2-2-2 (SDRAM), = 32-32-32 (DDR4 / LP DDR4 / LP DDR5 / LP DDR4) B = 2.5(3)-3-3 P = 15-15-15 C = 4-4-4 R = 16-16-16 D = 5-5-5 T = 17-17-17 E = 6-6-6 U = 18-18-18 F = 7-7-7 Q = 19-19-19 G = 8-8-8 S = 22-22-22 H = 9-9-9 V = 21-21-21 J = 10-10-10 W =20-20-20 K = 11-11-11 X = 24-24-24 L = 12-12-12 Y = 28-28-28 M = 13-13-13 Z = 36-36-36 N = 14-14-14																							
DRAM Volatge 12 =1.2V 11 = 1.1V 13 = 1.35V 1A = 1.05V 15 = 1.5V 2A = S2A 18 = 1.8V 2B = S2B 25 = 2.5V 4A = S4A 33 = 3.3V 4B = S4B																																															
DRAM Generation S = SDRAM K = LP DDR1 D = DDR L = LP DDR2 T = DDR2 M = LP DDR3 H = DDR3 N = LP DDR4 Q = DDR4 P = LP DDR5 or LP DDR5x V = DDR5 R = LP DDR4X J = LP SDR U = LP DDR4 or LP DDR4X																																															
DRAM Density 1G = 1 Gbit 32 = 32 Gbit 2G = 2 Gbit 64 =64 Mbit (for SDR)/ 64 Gbit (for LPD4/x) 4G = 4 Gbit 128 = 128 Mbit 8G = 8 Gbit 256 = 256 Mbit 16 = 16 Gbit 512 = 512 Mbit																																															
Number of IOs of Device 40 = x4 16 = x16 80 = x8 32 = x32																																															
Die Numbers 0 = Monolytic 4 = 4 dies 2 = 2 dies 6 = 6 dies																																															
Die Revision A = Frist product C = Third product B = Second product D = Fourth product																																															
Package C = FBGA black T = TSOPII black F = FBGA green E = TSOPII green L = FCBGA G = TSOP stack green B = FBGA green Package = 7.5*13.5mm H = FBGA green low alpha I = FBGA green low alpha and 0.43 ball size																								Speed Bin 75 = 133 Mbps 09 = 2133 Mbps 7 = 143 Mbps 08 = 2400 Mbps 6 = 166 Mbps 07 = 2666 Mbps 5 = 400 Mbps 05 = 2932 Mbps 4 = 500 Mbps 06 = 3200 Mbps 37 = 534 Mbps 03 = 3733 Mbps 3 = 666 Mbps 04 = 4266 Mbps 25 = 800 Mbps 20 = 4800 Mbps 19 = 1066 Mbps 21 = 5500 Mbps 15 = 1333 Mbps 22 = 6000 Mbps 13 = 1600 Mbps 23 = 6400 Mbps 11 = 1866 Mbps																							
																								Power - = Standard L= Low power																							